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# **FDMS8680**

# October 2014

# N-Channel PowerTrench<sup>®</sup> MOSFET 30V, 35A, 7.0m $\Omega$

#### **Features**

- Max  $r_{DS(on)}$  = 7.0m $\Omega$  at  $V_{GS}$  = 10V,  $I_D$  = 14A
- Max  $r_{DS(on)}$  = 11.0m $\Omega$  at  $V_{GS}$  = 4.5V,  $I_D$  = 11.5A
- $\blacksquare$  Advanced Package and Silicon combination for low  $r_{DS(on)}$  and high efficiency
- MSL1 robust package design
- RoHS Compliant

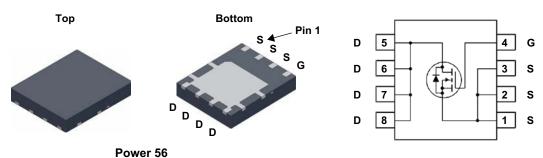


#### **General Description**

The FDMS8680 has been designed to minimize losses in power conversion application. Advancements in both silicon and package technologies have been combined to offer the lowest  $r_{\text{DS}(\text{on})}$  while maintaining excellent switching performance.

#### **Applications**

- Low Side for Synchronous Buck to Power Core Processor
- Secondary Side Synchronous Rectifier
- Low Side Switch in POL DC/DC Converter
- Oring FET/ Load Switch



# MOSFET Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter			Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage			30	V
V <sub>GS</sub>	Gate to Source Voltage			±20	V
	Drain Current -Continuous (Package limited)	T <sub>C</sub> = 25°C		35	
	-Continuous (Silicon limited)	T <sub>C</sub> = 25°C		63	1 ,
I <sub>D</sub>	-Continuous	T <sub>A</sub> = 25°C	(Note 1a)	14	A
	-Pulsed			100	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	216	mJ
В	Power Dissipation	T <sub>C</sub> = 25°C		50	W
P <sub>D</sub>	Power Dissipation	T <sub>A</sub> = 25°C	(Note 1a)	2.5	]
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature R	ange		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case		2.5	°C/W
R <sub>e.IA</sub>	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS8680	FDMS8680	Power 56	13"	12mm	3000units

# **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, referenced to 25°C		24		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V			1	μА
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.0	1.8	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, referenced to 25°C		-5.7		mV/°C
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 14A		5.5	7.0	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 4.5V, I_D = 11.5A$		8.5	11.0	mΩ
, ,	ļ į	V <sub>GS</sub> = 10V, I <sub>D</sub> = 14A, T <sub>J</sub> = 125°C		8.2	10.5	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DD</sub> = 10V, I <sub>D</sub> = 14A		72		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	\\ -45\\\\ -0\\	1195	1590	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz	555	740	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1101112	95	145	pF
$R_a$	Gate Resistance	f = 1MHz	0.8	4.0	Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		$V_{DD} = 15V, I_{D} = 14A,$ $V_{GS} = 10V, R_{GEN} = 6\Omega$		9	18	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 15V, I <sub>D</sub> = 14			3	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> - 10V, K <sub>GEN</sub> -	$V_{GS} = 10V, R_{GEN} = 6\Omega$		21	34	ns
t <sub>f</sub>	Fall Time				2	10	ns
$Q_g$	Total Gate Charge	V <sub>GS</sub> = 0V to 10V			18	26	nC
Qg	Total Gate Charge	V <sub>GS</sub> = 0V to 5V	$V_{GS} = 0V \text{ to } 5V$ $V_{DD} = 15V,$ $I_{D} = 14A$		10	14	nC
$Q_{gs}$	Gate to Source Charge		1 <sub>D</sub> - 14A		3.2		nC
$Q_{gd}$	Gate to Drain "Miller" Charge				2.7		nC

#### **Drain-Source Diode Characteristics**

$V_{SD}$	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 14A (Note 2)	0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	  -   I⊏ = 14A. di/dt = 100A/us	27	44	ns
Q <sub>rr</sub>	Reverse Recovery Charge	- 14A, α//αι – 100A/μs	15	27	nC

<sup>1.</sup> R<sub>0,1</sub> is determined with the device mounted on a  $1\text{in}^2$  pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0,1</sub> is guaranteed by design while R<sub>0,0</sub> is determined by the user's board design.



a. 50°C/W when mounted on a 1in² pad of 2 oz copper.



b. 125°C/W when mounted on a minimum pad of 2 oz copper.

<sup>2.</sup> Pulse Test: Pulse Width <  $300\mu$ s, Duty cycle < 2.0%. 3. Starting T<sub>J</sub> = 25°C, L = 3mH, I<sub>AS</sub> = 12A, V<sub>DD</sub> = 30V, V<sub>GS</sub> = 10V.

### Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

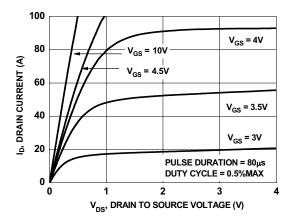


Figure 1. On-Region Characteristics

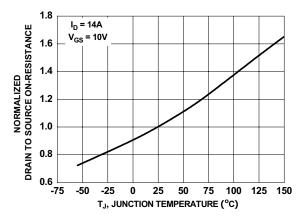


Figure 3. Normalized On-Resistance vs Junction Temperature

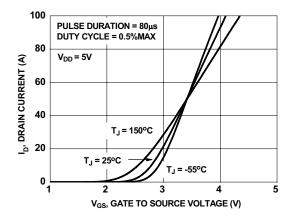


Figure 5. Transfer Characteristics

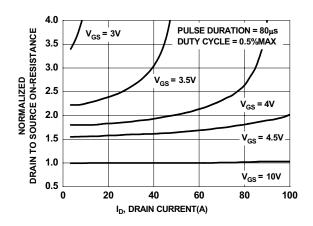


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

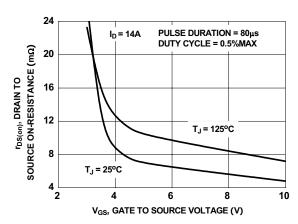


Figure 4. On-Resistance vs Gate to Source Voltage

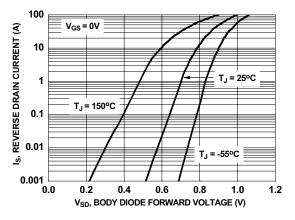


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

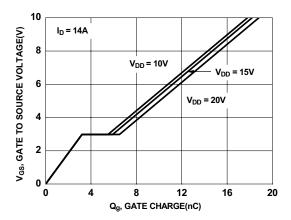


Figure 7. Gate Charge Characteristics

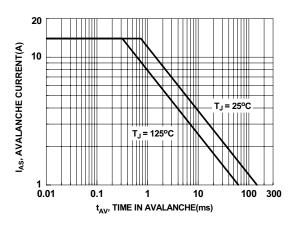


Figure 9. Unclamped Inductive Switching Capability

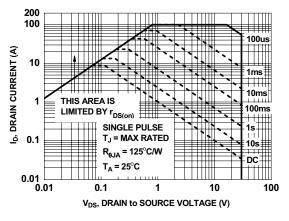


Figure 11. Forward Bias Safe Operating Area

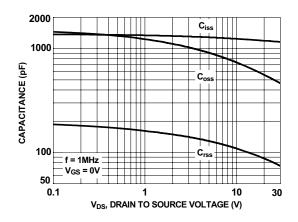


Figure 8. Capacitance vs Drain to Source Voltage

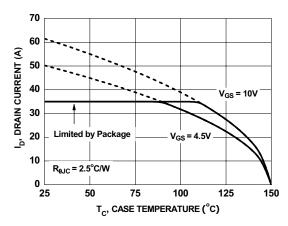


Figure 10. Maximum Continuous Drain Current vs Case Temperature

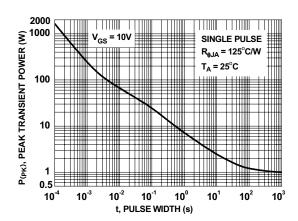


Figure 12. Single Pulse Maximum Power Dissipation

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

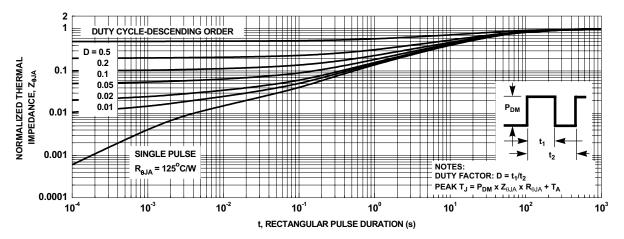


Figure 13. Transient Thermal Response Curve



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